PATENT ASSIGNMENT

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Ki Jun YUN	12/22/2008

RECEIVING PARTY DATA

Name:	Dongbu HiTek Co., Ltd.
Street Address:	891-10 Daechi-dong, Gangnam-gu
City:	Seoul
State/Country:	KOREA, REPUBLIC OF
Postal Code:	135-280

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12341864

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	SPO200805-0242US
NAME OF SUBMITTER:	Andrew D. Fortney, Reg. No. 34,600

Total Attachments: 1
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OP $40.00 12341864

Attorney Docket No.: **SPO200805-0242US**

ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, the undersigned,

Ki Jun YUN

who have created a certain invention for which an application for United States Letters Patent was executed by me concurrently herewith and entitled:
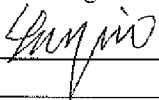
Image Sensor and Method for Manufacturing the Same

Do hereby sell, assign and transfer to **Dongbu HiTek Co., Ltd.** , a corporation of **Republic of Korea** , having a place of business at **891-10, Daechi-dong, Gangnam-gu, Seoul 135-280 / Republic of Korea** , its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

Agree that **Dongbu HiTek Co., Ltd.** , hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and

Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

IN TESTIMONY WHEREOF I have hereunto set MY signature on the date indicated below.

Full Name of Sole/First Inventor: **Ki Jun YUN**	
Inventor's Signature:	Date: Month/Day/Year December / 22 / 2008

Full Name of Second Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Customer No. 36872